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HIGH DIODE

SS32 THRU SS320

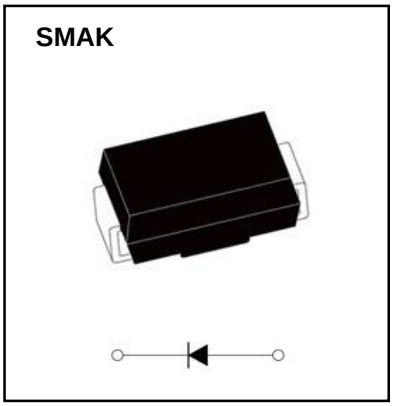
HD—AK55

SMAK Plastic-Encapsulate Diodes

Schottky Rectifier

Features

- I_O 3A
- VRRM 20V-200V
- High surge current capability
- Polarity: Color band denotes cathode



Applications

- Rectifier

Marking

- SS3X

  X：From 2 To 20

Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	SS3								
				2	3	4	5	6	8	10	15	20
Repetitive Peak Reverse Voltage	V_{RRM}	V		20	30	40	50	60	80	100	150	200
Maximum RMS Voltage	V_{RMS}	V		14	21	28	35	42	56	70	105	140
Average Forward Current	$I_{F(AV)}$	A	60HZ Half-sine wave, Resistance load, TL(Fig.1)	3.0								
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave ,1 cycle , Ta =25℃	100								
Junction Temperature	T_J	℃		-55~+125				-55~+150				
Storage Temperature	T_{STG}	℃		-55 ~ +150								

Electrical Characteristics (T_a=25℃Unless otherwise specified)

Item	Symbol	Unit	Test Condition		SS3								
					2	3	4	5	6	8	10	15	20
Peak Forward Voltage	V_F	V	I_F=3.0A		0.55			0.70		0.85		0.95	
Peak Reverse Current	I_{RRM1}	mA	$V_{RM}=V_{RRM}$	Ta =25℃	0.5					0.1			
	I_{RRM2}			Ta =100℃	10			5.0					
Thermal Resistance(Typical)	$R_{\theta J-A}$	℃/W	Between junction and ambient		55[1)]								
	$R_{\theta J-L}$		Between junction and terminal		17[1)]								

Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

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Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

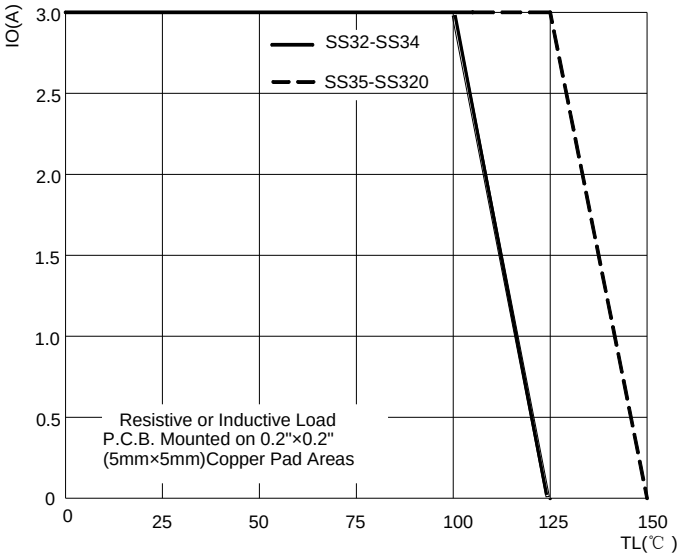


FIG.2: MAXIMUM NON-REPETITIVE FORWARD URGE CURRENT

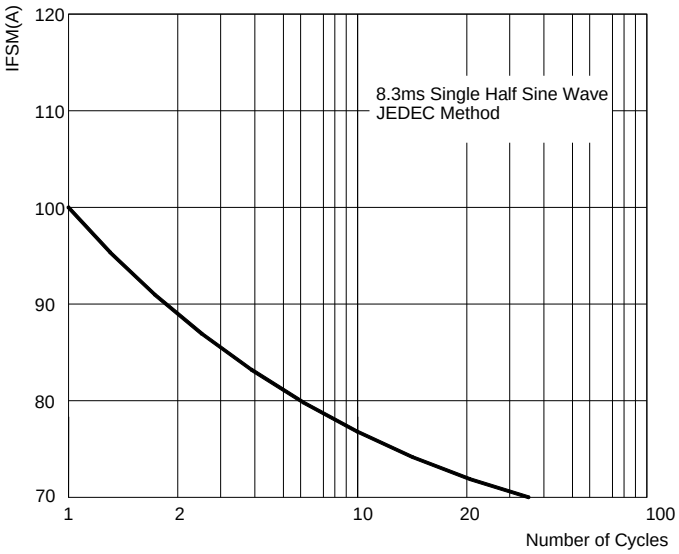


FIG.3: TYPICAL FORWARD CHARACTERISTICS

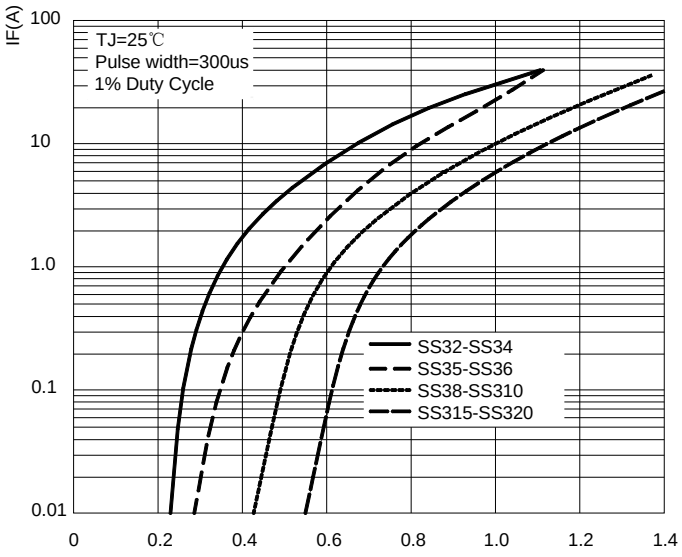
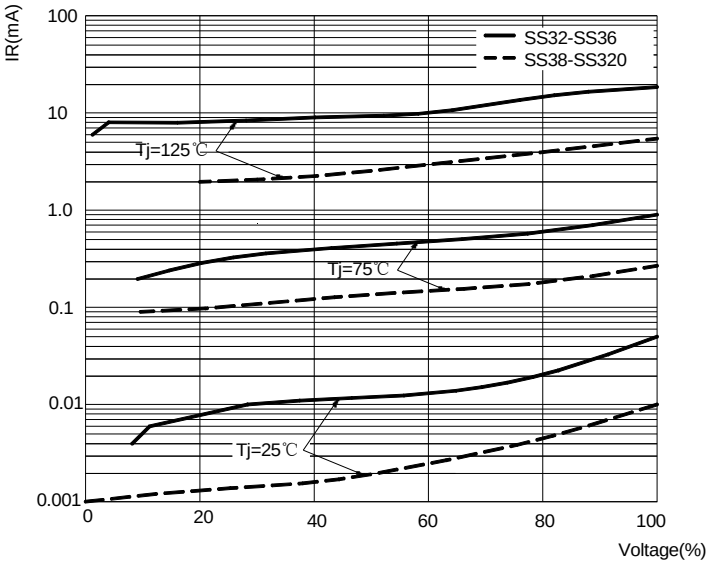
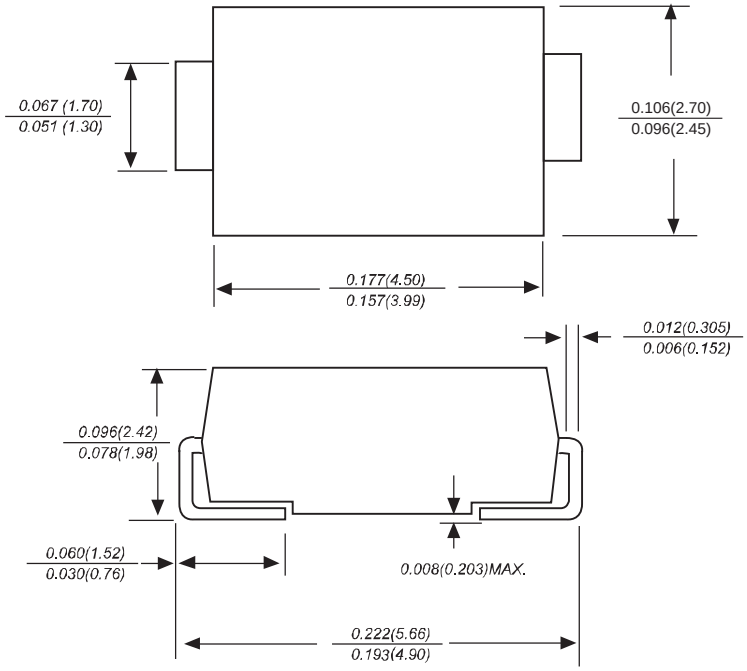


FIG.4：TYPICAL REVERSE CHARACTERISTICS



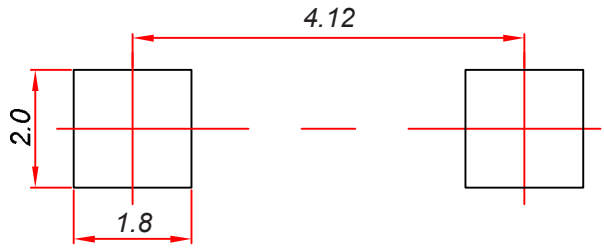
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SMAK Package Outline Dimensions



Dimensions in inches and (millimeters)

SMAK Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

NOTICE

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Reel Taping Specifications For Surface Mount Devices-SMA

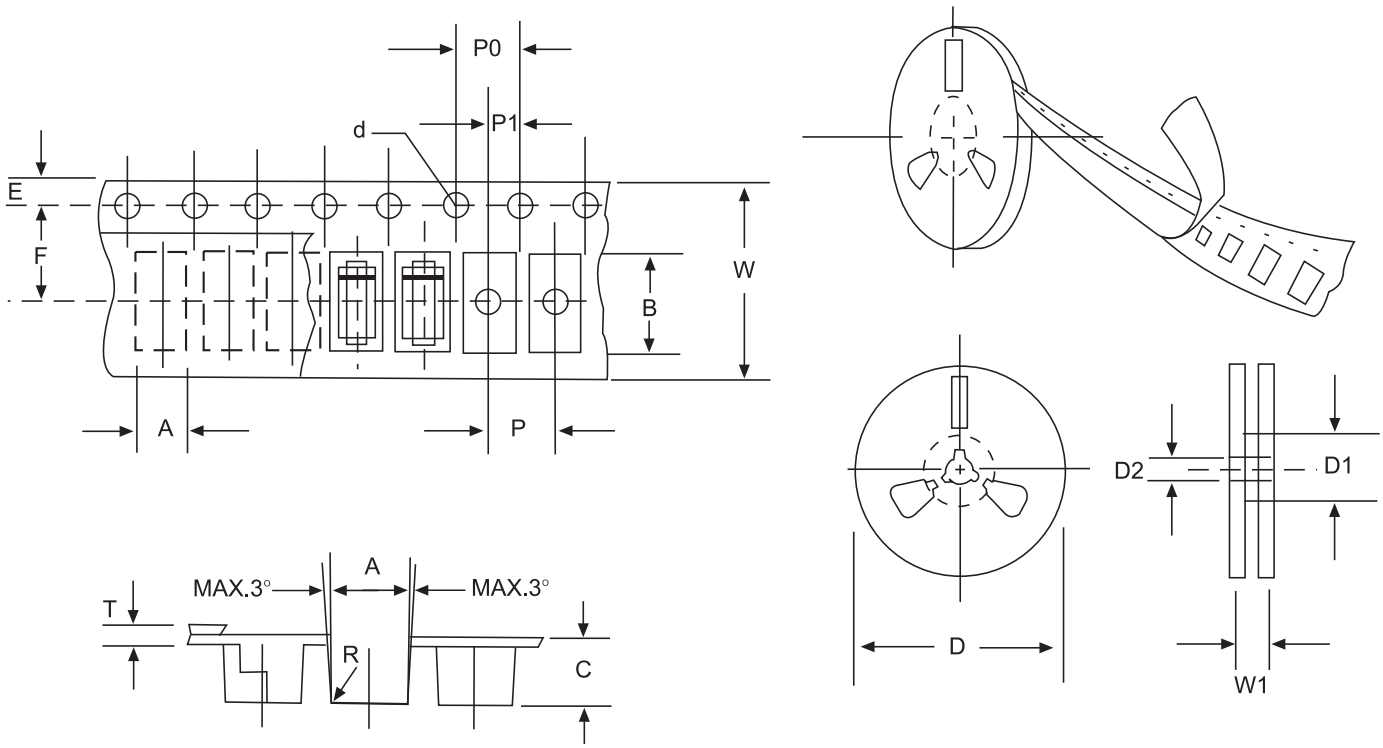


FIG:CONFIGURATION OF AXIAL TAPING

ITEM	SYMBOL	SMA mm(inch)
Carrier width	A	2.79±0.1(0.110±0.004)
Carrier length	B	5.33±0.1(0.210±0.004)
Carrier depth	C	2.36±0.1(0.093±0.004)
Sprocket hole	d	1.5±0.05 (0.059±0.0002)
Reel outside diameter	D	330/178±2.0(13/7.0±0.79)
Reel inner diameter	D1	8.0±0.2(0.315±0.008)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Stroket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.5±0.05(0.217±0.002)
Punch hole pitch	P	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	T	0.28±0.02(0.011±0.0008)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE:Devices are packde in accordance with EIA standard RS-481-A and specification given above.